

Half-Duplex RS-485/RS-422-Compatible Transceiver with AutoDirection Control

■ Description

The TK13487E +5V, half-duplex, $\pm 15\text{kV}$ ESD-protected RS-485/RS-422-compatible transceivers feature one driver and one receiver. It includes a hot-swap capability to eliminate false transitions on the bus during power-up or live insertion.

The TK13487E feature proprietary AutoDirection control. This architecture makes the devices ideal for applications, such as isolated RS-485 ports, where the driver input is used in conjunction with the driver-enable signal to drive the differential bus. It is intended for half-duplex communications. It is available in an 8-pin SOIC package.

■ Features

- 1 transmitter and 1 receiver of the serial data of the standard RS-485
- Robust Protection Features for Telecom, Industrial, and Isolated Applications
- 5V Supply Voltage Range
- Operating temperature range: $-40 \sim +85^\circ\text{C}$
- Data rate: 0.5Mbps
- AutoDirection Saves Space and BOM Cost
- Allows Up to 128 Transceivers on the Bus, 1/4-unit load receiver
- Enhanced ESD Specifications:
 $\pm 15\text{kV}$ Extended ESD Protection

■ Ordering Information

Part Number	Package	Packing	Temperature(TA)	Package Qty	ESD
TK13487EEASA	SOIC-8	Reel	$-40^\circ\text{C} \sim 85^\circ\text{C}$	2500	$\pm 15\text{kV}$

Note: Please contact us to customize DIP packaging device.

■ Pin Description

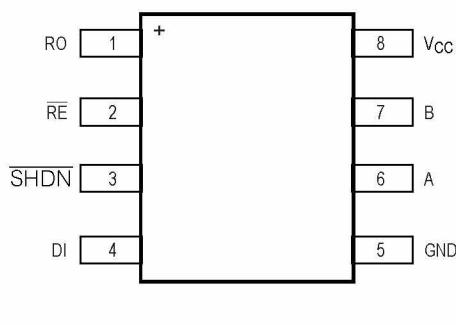


Table 1. Pin Description

PIN	NAME	FUNCTION
1	RO	Receiver Output. When receiver is enabled and $V(A) - V(B) > +200mV$, RO is high. If $V(A) - V(B) < -200mV$, RO is low.
2	\overline{RE}	Receiver Output Enable. Drive \overline{RE} low to enable RO. Drive \overline{RE} high to let the AutoDirection circuit control the receiver. \overline{RE} is a hot-swap input.
3	\overline{SHDN}	Shutdown. Drive \overline{SHDN} high to let the device operate in normal operation. Drive \overline{SHDN} low to put the part in shutdown.
4	DI	Driver Input. Drive DI low to force noninverting output low and inverting output high. Drive DI high to force noninverting output high and inverting output low. DI is an input to the internal state machine.
5	GND	Ground
6	A	Noninverting RS-485/RS-422 Receiver Input and Driver Output
7	B	Inverting RS-485/RS-422 Receiver Input and Driver Output
8	V_{CC}	Positive Supply. $V_{CC} = +5V \pm 5\%$. Bypass V_{CC} with a $0.1\mu F$ ceramic capacitor to ground.

Functional Diagram

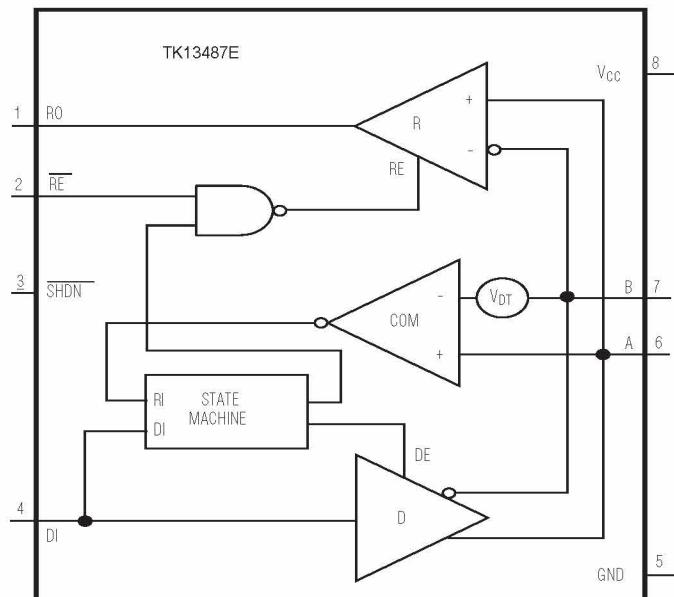


Table 2. Function Tables Transmitter Truth Table

TRANSMITTING					
INPUTS			ACTION	OUTPUTS	
SHDN	DI	A-B > V _{DT}		A	B
H	L	X	Turn driver ON	L	H
H	H	False	If driver was OFF, keep it OFF	HIGH IMPEDANCE	HIGH IMPEDANCE
H	H	False	If driver was ON, keep it ON	H	L
H	H	True	Turn driver OFF	HIGH IMPEDANCE	HIGH IMPEDANCE
L	X	X	X	SHUTDOWN	

Note : H – high level, L – low level , X –don't care

Table 3. Function Tables Receiver Truth Table

RECEIVING					
INPUTS				OUTPUT	
SHDN	RE	A-B	DRIVER STATE	RECEIVER STATE	RO
H	L	≥+200mV	X	ON	H
H	L	≤-200mV	X	ON	L
H	H	X	ON	OFF	HIGH IMPEDANCE
H	H	≥+200mV	OFF	ON	H
H	H	≤-200mV	OFF	ON	L
L	X	X	X	X	SHUTDOWN

Note : H – high level, L – low level , X –don't care

Table 4. Recommended Operating Condition

Symbol	Parameter	Limit		Unit
		min	max	
V_{CC}	Supply voltage	4.75	5.25	V
V_{IL}	Input low voltage SHDN, RE, DI	0	0.8	V
V_{IH}	Input high voltage SHDN, RE, DI	2.0	V_{CC}	V
V_{OD}	Transmitter output voltage	-7.0	12.0	V
V_{IR}	Receiver input voltage	-7.0	12.0	V
V_{OR}	Receiver output voltage	0	V_{CC}	V
V_{TH}	Receiver differential threshold voltage	$ \pm 50 $	$ \pm 200 $	V
T	Ambient temperature	-40	85	°C

Table 5. Maximum Ratings

Symbol	Parameter	Limit		Unit
		min	max	
V_{CC}	Supply voltage	-0.3	6.0	V
V_{IL}	SHDN, RE, DI	—	-0.3	V
V_{OD}	Transmitter output voltage	-8	13	V
V_{IR}	Receiver input voltage	-8	13	V
V_{OR}	Receiver output voltage	-0.3	$V_{CC}+0.3$	V

* Stresses beyond those listed under "maximum ratings" may cause permanent damage to the device.

These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Table 6. Electrical Parameters

(VCC = +5V ±5%, TA = TMIN to TMAX, Typical values are at VCC = +5V and TA = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Differential Driver Output	VOD	RDIFF = 100Ω, Figure 1	2.0	VCC		
		RDIFF = 54Ω, Figure 1	1.5			V
		No load		VCC		
Driver Common-Mode Output Voltage	VOC	RL = 100Ω or 54Ω, Figure 1	VCC / 2	3		V
Driver Disable Threshold	VDT	Figure 2 (Note 1)	+0.6	+1		V
Input-High Voltage	VIH	DI, SHDN, RE	2.0			V
Input-Low Voltage	VL	DI, SHDN, RE		0.8		V
Input Current	IIN	DI, SHDN, RE		±1		µA
Driver Short-Circuit Output Current (Note 2)	IOSD	0V ≤ VOUT ≤ +12V	+50	+250		mA
		-7V ≤ VOUT ≤ 0V	-250	-50		
Driver Short-Circuit Foldback Output Current (Note 2)	IOSDF	(VCC - 1V) ≤ VOUT ≤ +12V	20			mA
		-7V ≤ VOUT ≤ 0V		-20		
RECEIVER						
Input Current (A and B)	IA, B	DI = VCC, VCC = GND or +5V	VIN = +12V	250		µA
			VIN = -7V	-200		
Receiver Differential Threshold Voltage	VTH	-7V ≤ VCM ≤ +12V	-200	+200		mV
Receiver Input Hysteresis	ΔVTH	VA + VB = 0V	25			mV
Output-High Voltage	VOH	IO = -1.6mA, VA - VB > VTH	VCC - 1.5			V
Output-Low Voltage	VOL	IO = 1mA, VA - VB < -VTH	0.4			V
Tri-State Output Current at Receiver	IOZR	0V ≤ VO ≤ VCC		±1		µA
Receiver Input Resistance	RIN	-7V ≤ VCM ≤ +12V	48			kΩ
Receiver Output Short-Circuit Current	IOSR	0V ≤ VRO ≤ VCC	±7	±95		mA
POWER SUPPLY						
Supply Voltage	VCC		4.75	5.25		V
Supply Current	ICC	SHDN = 1, RE = 0, no load		4.5		mA
Shutdown Supply Current	ISHDN	SHDN = 0		10		µA
ESD PROTECTION						
ESD Protection (A, B)		Air Gap Discharge IEC 61000-4-2 (TK13487E)	±15			kV
		Human Body Model	±15			
ESD Protection (All Other Pins)		Human Body Model	±2			kV

Table 7.Switching Characteristics

($V_{CC} = +5V \pm 5\%$, $T_A = T_{MIN}$ to T_{MAX} . Typical values are at $V_{CC} = +5V$ and $T_A = +25^\circ C$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Driver Propagation Delay	t _{DPLH}	$R_L = 110\Omega$, $C_L = 50pF$, Figures 2 and 3	200	1000		ns
	t _{DPHL}		200	1000		
Driver Differential Output Rise or Fall Time	t _{HL}	$R_L = 110\Omega$, $C_L = 50pF$, Figures 2 and 3	200	900		ns
	t _{LH}		200	900		
Maximum Data Rate			500			kbps
Driver Disable Delay	t _{DDD}	Figure 3		2500		ns
Driver Enable from Shutdown to Output High	t _{DZH(SHDN)}	Figure 4		5.5		μs
Driver Enable from Shutdown to Output Low	t _{DZL(SHDN)}	Figure 4		5.5		μs
Time to Shutdown	t _{SHDN}		50	340	700	ns
RECEIVER						
Receiver Propagation Delay	t _{RPLH}	$C_L = 15pF$, Figures 5 and 6	80			ns
	t _{RPHL}		80			
Receiver Output Skew	t _{RSKEW}	$C_L = 15pF$, Figure 6		13		ns
Maximum Data Rate			500			kbps
Receiver Enable to Output High	t _{RZH}	Figure 7		50		ns
Receiver Enable to Output Low	t _{RZL}	Figure 7		50		ns
Receiver Disable Time from High	t _{RHZ}	Figure 7		50		ns
Receiver Disable Time from Low	t _{RLZ}	Figure 7		50		ns
Receiver Enable from Shutdown to Output High	t _{RZH(SHDN)}	Figure 8		2200		ns
Receiver Enable from Shutdown to Output Low	t _{RLZ(SHDN)}	Figure 8		2200		ns
Receiver Enable Delay	t _{RED}	Figure 3		70		ns
Time to Shutdown	t _{SHDN}		50	340	700	ns

Note 1: This is a differential voltage from A to B that the driving device must see on the bus to disable its driver.

Note 2: The short-circuit output current applied to peak current just prior to foldback current limiting. The short-circuit foldback

out-put current applies during current limiting to allow a recovery from bus contention.

Test and Timing Diagrams

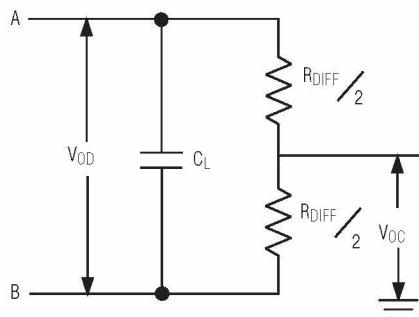


Figure 1. Driver DC Test Load

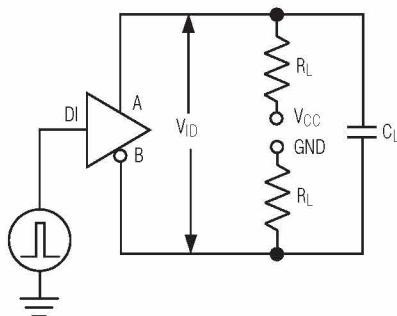


Figure 2. Driver Timing Test Circuit

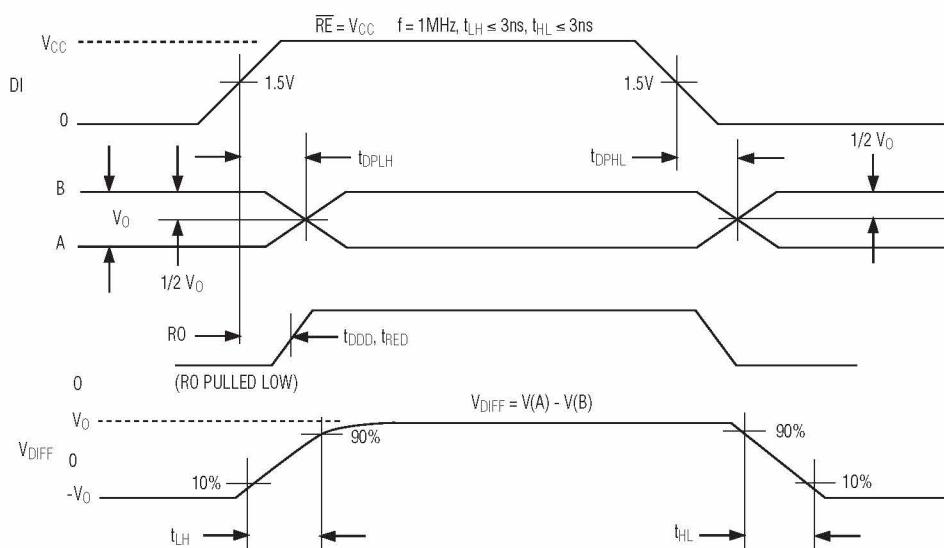


Figure 3. Driver Propagation Delays

Test and Timing Diagrams(continued)

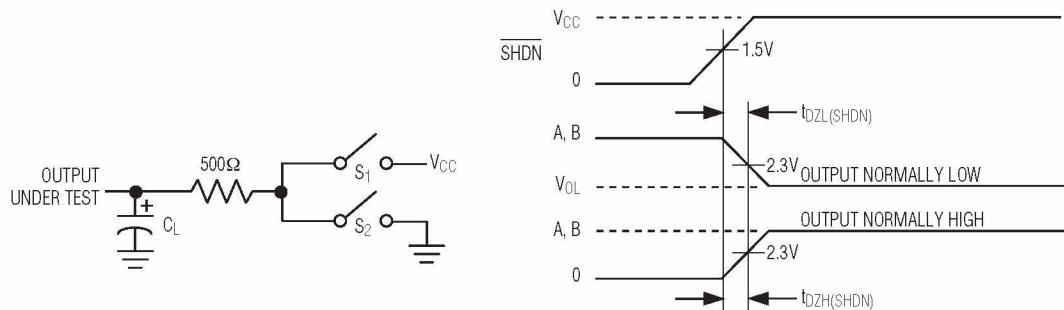


Figure 4. Driver Enable and Disable Times (t_{DZH} , t_{DHZ})

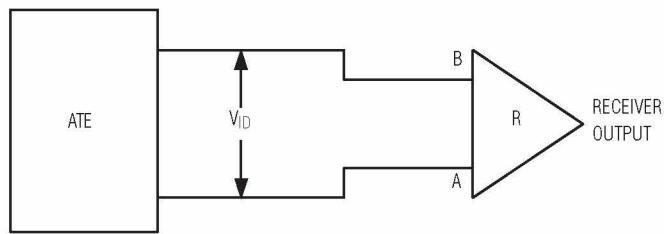


Figure 5. Driver Enable and Disable Times (t_{DZL} , t_{DLZ})

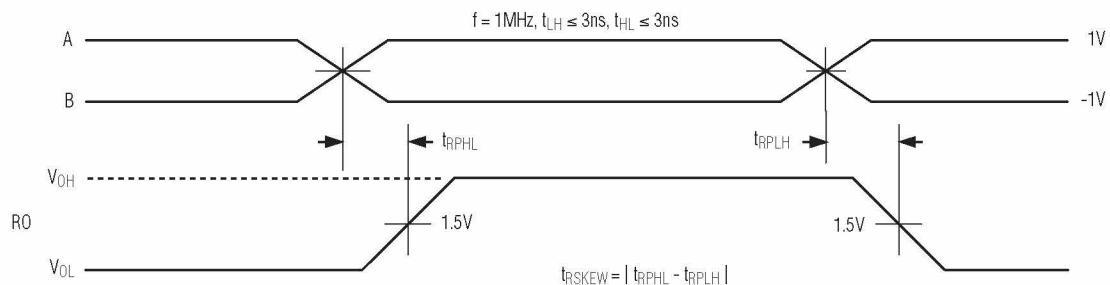


Figure 6. Receiver Propagation Delay Test Circuit

Test and Timing Diagrams(continued)

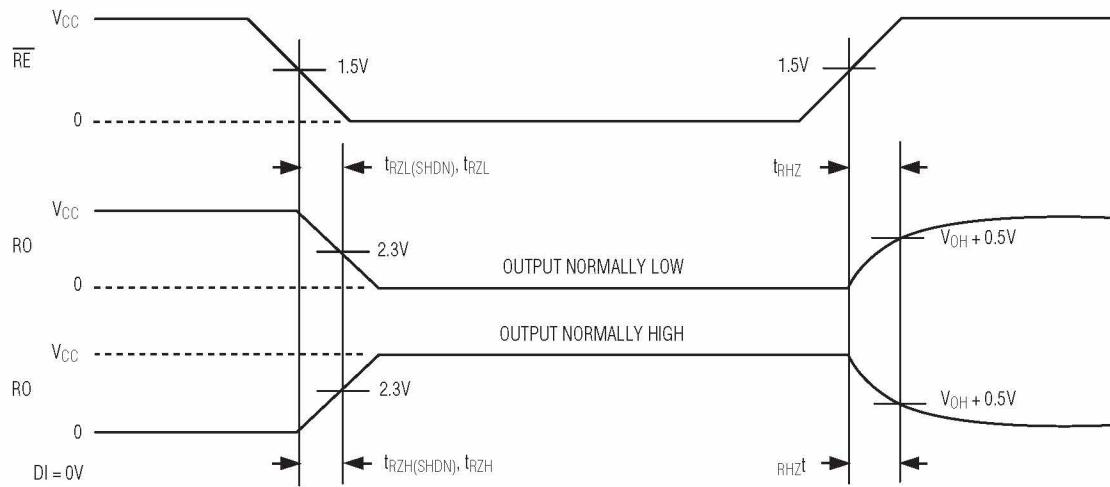


Figure 7. Receiver Propagation Delays

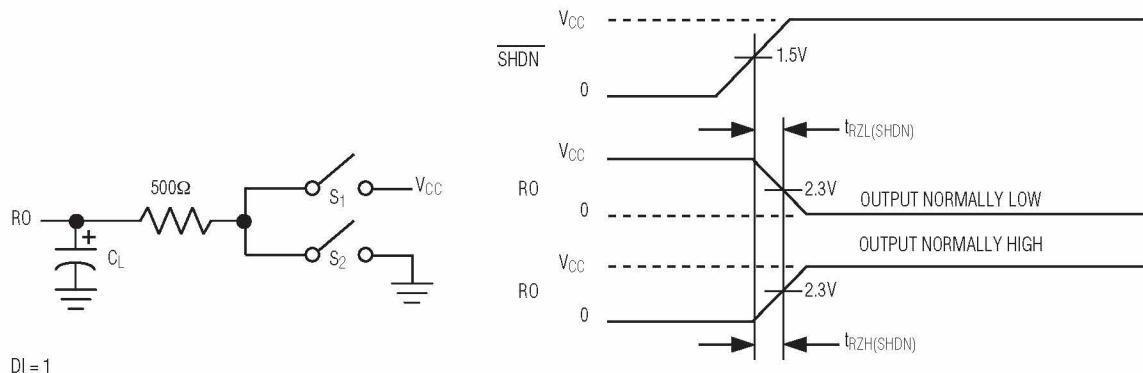
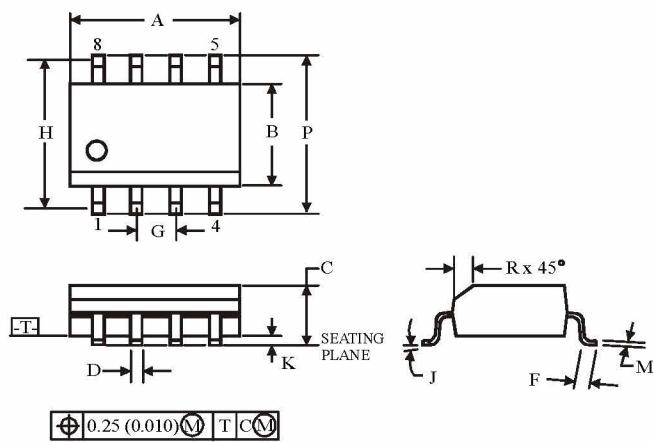


Figure 8. Receiver Enable and Disable Times

■ Package Dimensions
SOIC8

NOTES:

1. Dimensions A and B do not include mold flash or protrusion.
2. Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B - 0.25 mm (0.010) per side.

	Dimension, mm	
Symbol	MIN	MAX
A	4.8	5
B	3.8	4
C	1.35	1.75
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	5.72	
J	0°	8°
K	0.1	0.25
M	0.19	0.25
P	5.8	6.2
R	0.25	0.5